

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

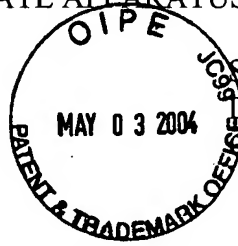
Applicant: Bryan M. White et al.

Title: THERMAL INTERMEDIATE APPARATUS, SYSTEMS, AND METHODS

Docket No.: 884.864US1

Filed: December 30, 2003

Examiner: Unknown



Serial No.: 10/748565

Due Date: N/A

Group Art Unit: Unknown

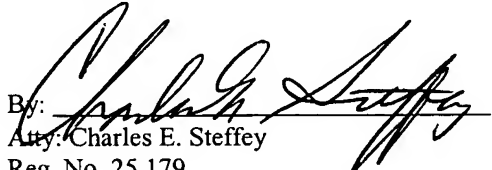
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

- ☒ A return postcard.
- ☒ A Supplemental Information Disclosure Statement (2 pgs.), Form 1449 (1 pg.), and copies of 3 cited documents (Copies of US Patent/Publication documents NOT enclosed; application filed after June 30, 2003).
- ☒ A Communication Concerning Related Applications (2 pages).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
Customer Number 21186

By: 
Atty: Charles E. Steffey
Reg. No. 25,179

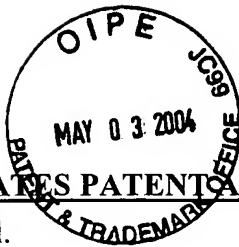
CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 29 day of April, 2004.

KACIA LEE
Name

Kacia Lee
Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
(GENERAL)

S/N 10/748565



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Bryan M. White et al.	Examiner:	Unknown
Serial No.:	10/748565	Group Art Unit:	Unknown
Filed:	December 30, 2003	Docket:	884.864US1
Title:	THERMAL INTERMEDIATE APPARATUS, SYSTEMS, AND METHODS		
Assignee:	Intel Corporation	Customer No.:	21186

COMMUNICATION CONCERNING RELATED APPLICATION(S)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>	<u>Title</u>
10/170313	June 12, 2002	884.564US1	INCREASING THERMAL CONDUCTIVITY OF THERMAL INTERFACE USING CARBON NANOTUBES AND CVD
10/024057	December 17, 2001	884.569US1	METHOD AND APPARATUS FOR PRODUCING ALIGNED CARBON NANOTUBE THERMAL INTERFACE STRUCTURE
10/738637	December 16, 2003	884.564US2	INCREASING THERMAL CONDUCTIVITY OF THERMAL INTERFACE USING CARBON NANOTUBES AND CVD

COMMUNICATION CONCERNING RELATED APPLICATIONS

Serial Number: 10/748565

Filing Date: December 30, 2003

Title: THERMAL INTERMEDIATE APPARATUS, SYSTEMS, AND METHODS

Assignee: Intel Corporation

Page 2

Dkt: 884.864US1 (INTEL)

Respectfully submitted,

BRYAN M. WHITE ET AL.

By Applicants' Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

P.O. Box 2938

Minneapolis, MN 55402

(612) 373-6970

Date

April 29, 2004

By

Charles E. Steffey

Charles E. Steffey

Reg. No. 25,179

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 29 day of April, 2004.

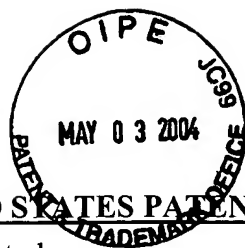
Name

KACIA LEE

Signature

Kacia Lee

S/N 10/748565



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Bryan M. White et al.	Examiner:	Unknown
Serial No.:	10/748565	Group Art Unit:	Unknown
Filed:	December 30, 2003	Docket:	884.864US1
Title:	THERMAL INTERMEDIATE APPARATUS, SYSTEMS, AND METHODS		
Assignee:	Intel Corporation	Customer No:	21186

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Supplemental Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Supplemental Information Disclosure Statement considered.

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Serial No : 10/748565

Filing Date: December 30, 2003

Title: THERMAL INTERMEDIATE APPARATUS, SYSTEMS, AND METHODS

Assignee: Intel Corporation

Page 2

Dkt: 884.864US1 (INTEL)

The present application is either a U.S. national patent application filed after June 30, 2003 or an international application that entered the national stage under 35 U.S.C. § 371 after June 30, 2003. Thus, Applicant believes that the U.S. Patent & Trademark Office has waived the requirement under 37 C.F.R. 1.98 (a)(2)(i) for submitting a copy of each cited U.S. patent and each U.S. patent application publication. The waiver is provided in a pre-OG notice from the U.S. Patent & Trademark Office entitled "Information Disclosure Statements May Be Filed Without Copies of U.S. Patents and Published Applications in Patent Applications filed after June 30, 2003" and dated July 11, 2003. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

BRYAN M. WHITE ET AL.

By their Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Attorneys for Intel Corporation

P.O. Box 2938

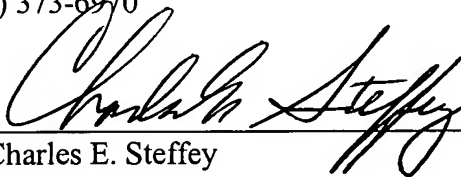
Minneapolis, Minnesota 55402

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Date

April 29, 2004

By



Charles E. Steffey

Reg. No. 25,179

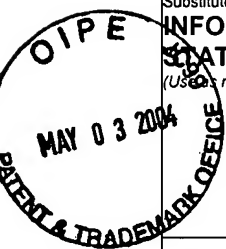
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Name

KACIA LEE

Signature

Kacia Lee



Substitute for form 1449A/PTO INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)	Complete if Known	
	Application Number	10/748565
	Filing Date	December 30, 2003
	First Named Inventor	White, Bryan
	Group Art Unit	Unknown
	Examiner Name	Unknown
Sheet 1 of 1	Attorney Docket No: 884.864US1	

US PATENT DOCUMENTS						
Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
	US-2003/0117770	06/26/2003	Montgomery, Stephen W.	361	687	12/20/2001
	US-5,316,080	05/31/1994	Banks, Bruce A., et al.	165	185	02/10/1993
	US-5,604,037	02/18/1997	Ting, Jyh-Ming, et al.	428	408	11/01/1994
	US-5,825,624	10/20/1998	Arnold, Judson V., et al.	361	708	02/05/1997
	US-5,837,081	11/17/1998	Ting, Jyh-Ming, et al.	156	89.26	03/13/1996
	US-5,965,267	10/12/1999	Nolan, Peter E., et al.	428	408	03/31/1998
	US-6,312,303	11/06/2001	Yaniv, Zvi, et al.	445	24	07/19/1999
	US-6,630,772	10/07/2003	Bower, Christopher A., et al.	313	311	04/22/1999

FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²
	EP-0538798	04/28/1993	Iguchi, T., et al.	H01L	23/373	
	EP-0689244	12/27/1995	Anthony, T. R.	H01L	23/373	

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		BELLAR, R J., et al., "High Conduction Thermal Interface Material", <u>IBM Technical Disclosure Bulletin</u> , 36 (10), (October 1, 1993), 581-583	

EXAMINER

DATE CONSIDERED